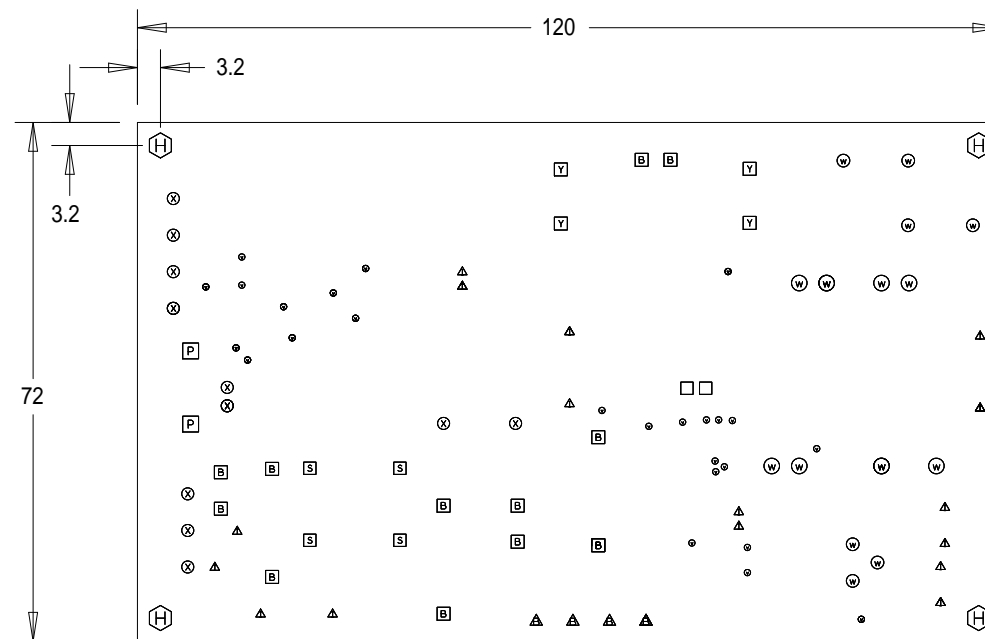


# SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	DFTM /2LAYERS
MINIMAL GAP	210um /8.0mils
MINIMAL SLIVER	210um /8.0mils
COPPER THICKNESS	35um(1oz)at START
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN TOP&BOT
SILKSCREEN	WHITE TOP&BOT
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
○	0.5 VIA	PLATED	25
△	0.8	PLATED	16
▣	1.0	PLATED	12
□	1.05	PLATED	2
▤	1.1	PLATED	4
▥	1.2	PLATED	4
⊗	1.4	PLATED	11
▲	1.5	PLATED	4
⊙	1.6	PLATED	7
⊗	1.65	PLATED	8
▣	2.2	PLATED	2
⊕	3.5	PLATED	4



rev3.1  
rev3  
rev2  
rev1

D11  
MaJ  
60W

W25/2021  
W49/2020  
W03/2020  
W39/2019

indice	Description	Date
Controle par :	Autorise par:	

<p>Board: <b>NCL30486LED2GEVB</b></p>	Definition CUT & DRILL DRAWING PLAN PERCAGE DETOURAGE	
	Subc. <b>DYPE TECH</b>	Dessine: e B Echelle: 1/1
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